

# DRAM MODULE

# KMM5322104CKU/CKUG

## KMM5322104CKU/CKUG Fast Page Mode with Extended Data Out 2M x 32 DRAM SIMM using 2Mx8 , 2K Refresh, 5V

### GENERAL DESCRIPTION

The Samsung KMM5322104CKU is a 2Mx32bits Dynamic RAM high density memory module. The Samsung KMM5322104CKU consists of four CMOS 2Mx8bits DRAMs in 28-pin SOJ package mounted on a 72-pin glass-epoxy substrate. A 0.1 or 0.22uF decoupling capacitor is mounted on the printed circuit board for each DRAM. The KMM5322104CKU is a Single In-line Memory Module with edge connections and is intended for mounting into 72 pin edge connector sockets.

### PERFORMANCE RANGE

Speed	t <sub>TRAC</sub>	t <sub>CAC</sub>	t <sub>RC</sub>	t <sub>HPC</sub>
-5	50ns	13ns	90ns	25ns
-6	60ns	15ns	110ns	30ns

### FEATURES

- Part Identification
  - KMM5322104CKU(2048 cycles/32ms Ref, SOJ, Solder)
  - KMM5322104CKUG(2048 cycles/32ms Ref, SOJ, Gold)
- Fast Page Mode with Extended Data Out
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh capability
- $\overline{\text{RAS}}$ -only and Hidden refresh capability
- TTL compatible inputs and outputs
- Single +5V±10% power supply
- JEDEC standard PDPin & pinout
- PCB : Height(1000mil), single sided component

### PIN CONFIGURATIONS

Pin	Symbol	Pin	Symbol
1	V <sub>ss</sub>	37	NC
2	DQ0	38	NC
3	DQ18	39	$\overline{\text{Vss}}$
4	DQ1	40	$\overline{\text{CAS0}}$
5	DQ19	41	$\overline{\text{CAS2}}$
6	DQ2	42	$\overline{\text{CAS3}}$
7	DQ20	43	$\overline{\text{CAS1}}$
8	DQ3	44	$\overline{\text{RAS0}}$
9	DQ21	45	Res( $\overline{\text{RAS1}}$ )
10	V <sub>cc</sub>	46	NC
11	NC	47	$\overline{\text{W}}$
12	A0	48	NC
13	A1	49	DQ9
14	A2	50	DQ27
15	A3	51	DQ10
16	A4	52	DQ28
17	A5	53	DQ11
18	A6	54	DQ29
19	A10	55	DQ12
20	DQ4	56	DQ30
21	DQ22	57	DQ13
22	DQ5	58	DQ31
23	DQ23	59	V <sub>cc</sub>
24	DQ6	60	DQ32
25	DQ24	61	DQ14
26	DQ7	62	DQ33
27	DQ25	63	DQ15
28	A7	64	DQ34
29	Res(A11)	65	DQ16
30	V <sub>cc</sub>	66	NC
31	A8	67	PD1
32	A9	68	PD2
33	Res( $\overline{\text{RAS1}}$ )	69	PD3
34	$\overline{\text{RAS0}}$	70	PD4
35	NC	71	NC
36	NC	72	V <sub>ss</sub>

### PIN NAMES

Pin Name	Function
A0 - A10	Address Inputs
DQ0 - DQ31	Data In/Out
$\overline{\text{W}}$	Read/Write Enable
$\overline{\text{RAS0}}$	Row Address Strobe
$\overline{\text{CAS0}}$ - $\overline{\text{CAS3}}$	Column Address Strobe
PD1 -PD4	Presence Detect
V <sub>cc</sub>	Power(+5V)
V <sub>ss</sub>	Ground
NC	No Connection
Res	Reserved Pin

### PRESENCE DETECT PINS (Optional)

Pin	50NS	60NS
PD1	NC	NC
PD2	NC	NC
PD3	V <sub>ss</sub>	NC
PD4	V <sub>ss</sub>	NC

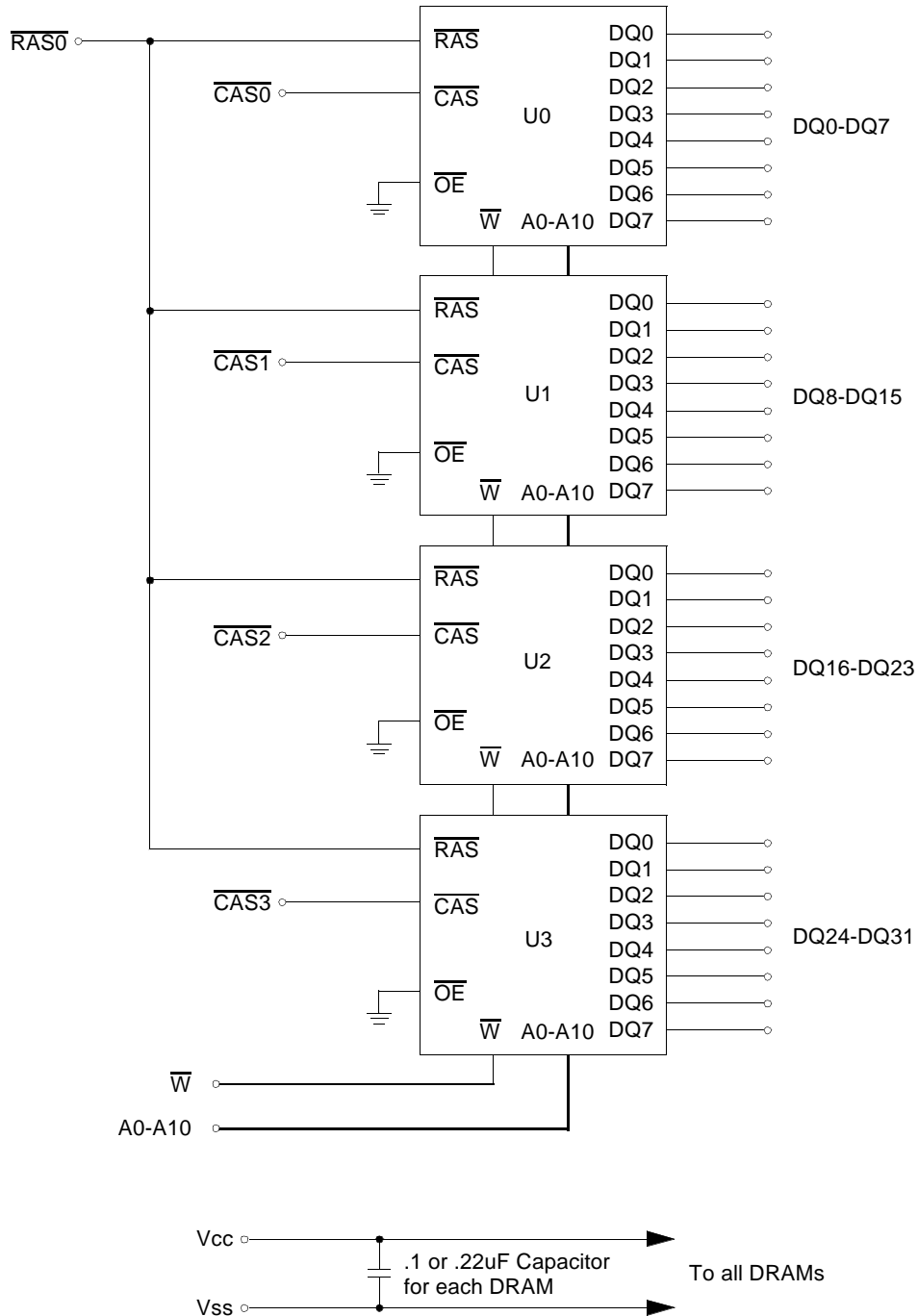
\* Pin connection changing available

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## FUNCTIONAL BLOCK DIAGRAM



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## ABSOLUTE MAXIMUM RATINGS \*

Item	Symbol	Rating	Unit
Voltage on any pin relative to Vss	V <sub>IN</sub> , V <sub>OUT</sub>	-1 to +7.0	V
Voltage on Vcc supply relative to Vss	V <sub>CC</sub>	-1 to +7.0	V
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C
Power Dissipation	P <sub>d</sub>	4	W
Short Circuit Output Current	I <sub>OS</sub>	50	mA

\* Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for intended periods may affect device reliability.

## RECOMMENDED OPERATING CONDITIONS (Voltage referenced to Vss, TA = 0 to 70°C)

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	V <sub>CC</sub>	4.5	5.0	5.5	V
Ground	V <sub>SS</sub>	0	0	0	V
Input High Voltage	V <sub>IH</sub>	2.4	-	V <sub>CC</sub> +1 <sup>*1</sup>	V
Input Low Voltage	V <sub>IL</sub>	-1.0 <sup>*2</sup>	-	0.8	V

\*1 : V<sub>CC</sub>+2.0V/20ns, Pulse width is measured at V<sub>CC</sub>.

\*2 : -2.0V/20ns, Pulse width is measured at V<sub>SS</sub>.

## DC AND OPERATING CHARACTERISTICS (Recommended operating conditions unless otherwise noted)

Symbol	Speed	KMM5322104CKU/CKUG		Unit
		Min	Max	
I <sub>CC1</sub>	-5	-	440	mA
	-6	-	400	mA
I <sub>CC2</sub>	Don't care	-	8	mA
I <sub>CC3</sub>	-5	-	440	mA
	-6	-	400	mA
I <sub>CC4</sub>	-5	-	360	mA
	-6	-	320	mA
I <sub>CC5</sub>	Don't care	-	4	mA
I <sub>CC6</sub>	-5	-	440	mA
	-6	-	400	mA
I <sub>I(L)</sub>	Don't care	-20	20	uA
I <sub>O(L)</sub>	Don't care	-5	5	uA
V <sub>OH</sub>	Don't care	2.4	-	V
V <sub>OL</sub>	Don't care	-	0.4	V

I<sub>CC1</sub> : Operating Current \* ( $\overline{RAS}$ ,  $\overline{CAS}$ , Address cycling @trc=min)

I<sub>CC2</sub> : Standby Current ( $\overline{RAS}=\overline{CAS}=\overline{W}=V_{IH}$ )

I<sub>CC3</sub> :  $\overline{RAS}$  Only Refresh Current \* ( $\overline{CAS}=V_{IH}$ ,  $\overline{RAS}$  cycling @trc=min)

I<sub>CC4</sub> : EDO Mode Current \* ( $\overline{RAS}=V_{IL}$ ,  $\overline{CAS}$  cycling : t<sub>HPC</sub>=min)

I<sub>CC5</sub> : Standby Current ( $\overline{RAS}=\overline{CAS}=\overline{W}=V_{CC}-0.2V$ )

I<sub>CC6</sub> :  $\overline{CAS}$ -Before- $\overline{RAS}$  Refresh Current \* ( $\overline{RAS}$  and  $\overline{CAS}$  cycling @trc=min)

I<sub>I(L)</sub> : Input Leakage Current (Any input 0≤V<sub>IN</sub>≤V<sub>CC</sub>+0.5V, all other pins not under test=0 V)

I<sub>O(L)</sub> : Output Leakage Current(Data Out is disabled, 0V≤V<sub>OUT</sub>≤V<sub>CC</sub>)

V<sub>OH</sub> : Output High Voltage Level (I<sub>OH</sub> = -5mA)

V<sub>OL</sub> : Output Low Voltage Level (I<sub>OL</sub> = 4.2mA)

\* **NOTE** : I<sub>CC1</sub>, I<sub>CC3</sub>, I<sub>CC4</sub> and I<sub>CC6</sub> are dependent on output loading and cycle rates. Specified values are obtained with the output open. I<sub>CC</sub> is specified as an average current. In I<sub>CC1</sub> and I<sub>CC3</sub>, address can be changed maximum once while  $\overline{RAS}=V_{IL}$ . In I<sub>CC4</sub>, address can be changed maximum once within one EDO mode cycle, t<sub>HPC</sub>.



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## CAPACITANCE (TA = 25°C, VCC=5V, f = 1MHz)

Item	Symbol	Min	Max	Unit
Input capacitance[A0-A10]	CIN1	-	35	pF
Input capacitance[ $\overline{W}$ ]	CIN2	-	40	pF
Input capacitance[ $\overline{RAS0}$ ]	CIN3	-	40	pF
Input capacitance[ $\overline{CAS0}$ - $\overline{CAS3}$ ]	CIN4	-	20	pF
Input/Output capacitance[ $\overline{DQ0-31}$ ]	CDQ	-	20	pF

## AC CHARACTERISTICS (0°C ≤ TA ≤ 70°C, VCC=5.0V ± 10%. See notes 1,2.)

Test condition : Vih/Vil=2.4/0.8V, Voh/Vol=2.0/0.8V, output loading CL=100pF

Parameter	Symbol	-5		-6		Unit	Note
		Min	Max	Min	Max		
Random read or write cycle time	tRC	90		110		ns	
Access time from $\overline{RAS}$	tRAC		50		60	ns	3,4,10
Access time from $\overline{CAS}$	tCAC		13		15	ns	3,4,5
Access time from column address	tAA		25		30	ns	3,10
$\overline{CAS}$ to output in Low-Z	tCLZ	3		3		ns	3
Output buffer turn-off delay from $\overline{CAS}$	tCEZ	3	13	3	15	ns	6,11,12
Transition time(rise and fall)	tr	2	50	2	50	ns	2
$\overline{RAS}$ precharge time	tRP	30		40		ns	
$\overline{RAS}$ pulse width	tRAS	50	10K	60	10K	ns	
$\overline{RAS}$ hold time	tRSH	13		15		ns	
$\overline{CAS}$ hold time	tCSH	40		50		ns	
$\overline{CAS}$ pulse width	tCAS	8	10K	10	10K	ns	13
$\overline{RAS}$ to $\overline{CAS}$ delay time	tRCD	20	37	20	45	ns	4
$\overline{RAS}$ to column address delay time	tRAD	15	25	15	30	ns	10
$\overline{CAS}$ to $\overline{RAS}$ precharge time	tCRP	5		5		ns	
Row address set-up time	tASR	0		0		ns	
Row address hold time	tRAH	10		10		ns	
Column address set-up time	tASC	0		0		ns	
Column address hold time	tCAH	8		10		ns	
Column address to $\overline{RAS}$ lead time	tRAL	25		30		ns	
Read command set-up time	tRCS	0		0		ns	
Read command hold time referenced to $\overline{CAS}$	tRCH	0		0		ns	8
Read command hold time referenced to $\overline{RAS}$	tRRH	0		0		ns	8
Write command hold time	tWCH	10		10		ns	
Write command pulse width	tWP	10		10		ns	
Write command to $\overline{RAS}$ lead time	tRWL	13		15		ns	
Write command to $\overline{CAS}$ lead time	tCWL	8		10		ns	
Data-in set-up time	tDS	0		0		ns	9
Data-in hold time	tDH	8		10		ns	9
Refresh period	tREF		32		32	ms	
Write command set-up time	tWCS	0		0		ns	7
$\overline{CAS}$ setup time( $\overline{CAS}$ -before- $\overline{RAS}$ refresh)	tCSR	5		5		ns	
$\overline{CAS}$ hold time( $\overline{CAS}$ -before- $\overline{RAS}$ refresh)	tCHR	10		10		ns	
$\overline{RAS}$ precharge to $\overline{CAS}$ hold time	tRPC	5		5		ns	
$\overline{CAS}$ precharge time ( $\overline{C}$ -B- $\overline{R}$ counter test)	tCPT	20		20		ns	



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## AC CHARACTERISTICS (0°C ≤ T<sub>A</sub> ≤ 70°C, V<sub>CC</sub> = 5.0V ± 10%. See notes 1,2.)

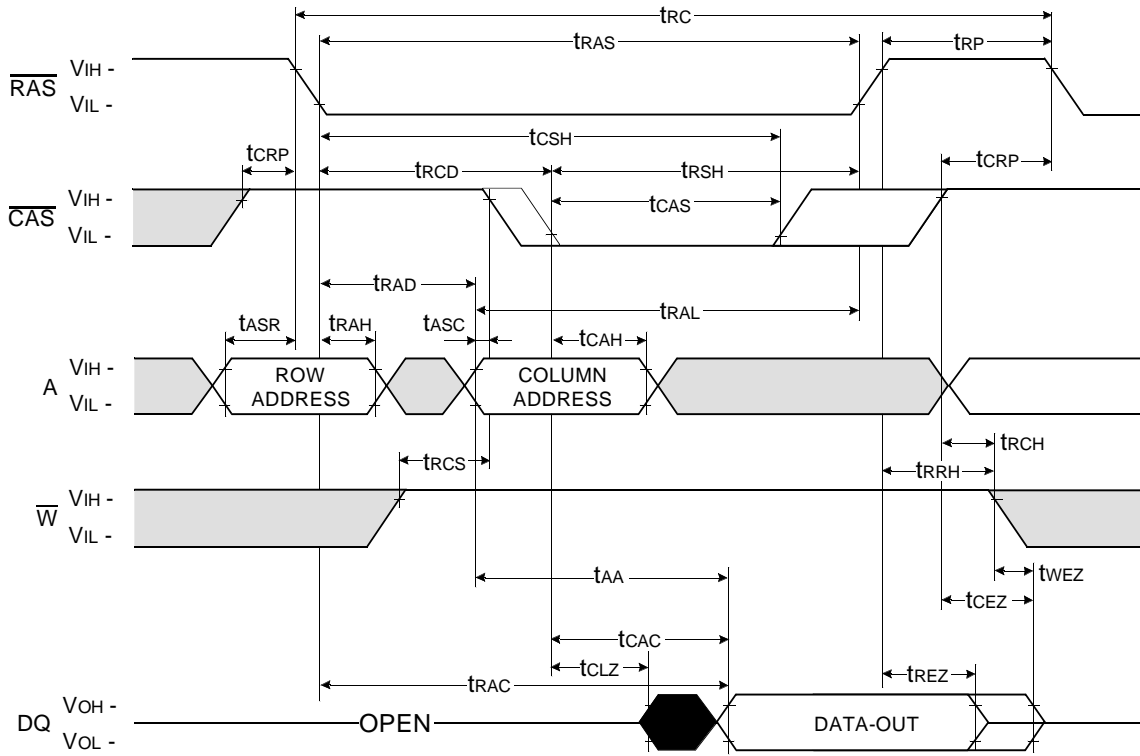
Test condition : V<sub>IH</sub>/V<sub>IL</sub> = 2.4/0.8V, V<sub>OH</sub>/V<sub>OL</sub> = 2.0/0.8V, output loading CL = 100pF

Parameter	Symbol	-5		-6		Unit	Note
		Min	Max	Min	Max		
Access time from $\overline{\text{CAS}}$ precharge	tCPA		30		35	ns	3
Hyper page mode cycle time	tHPC	25		30		ns	13
$\overline{\text{CAS}}$ precharge time from (Hyper Page Cycle)	tCP	8		10		ns	
$\overline{\text{RAS}}$ pulse width (Hyper Page Cycle)	tRASP	50	200K	60	200K	ns	
$\overline{\text{RAS}}$ hold time from $\overline{\text{CAS}}$ precharge	tRHCP	30		35		ns	
$\overline{\text{W}}$ to $\overline{\text{RAS}}$ precharge time ( $\overline{\text{C}}$ -B- $\overline{\text{R}}$ refresh)	tWRP	10		10		ns	
$\overline{\text{W}}$ to $\overline{\text{RAS}}$ hold time ( $\overline{\text{C}}$ -B- $\overline{\text{R}}$ refresh)	tWRH	10		10		ns	
Output data hold time	tDOH	5		5		ns	
Output buffer turn off delay from $\overline{\text{RAS}}$	tREZ	3	13	3	15	ns	6,11,12
Output buffer turn off delay from $\overline{\text{W}}$	tWEZ	3	13	3	15	ns	6,11
$\overline{\text{W}}$ to data delay	tWED	15		15		ns	
$\overline{\text{W}}$ pulse width (Hyper Page Cycle)	tWPE	5		5		ns	

## NOTES

- An initial pause of 200us is required after power-up followed by any 8  $\overline{\text{RAS}}$ -only or  $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$  refresh cycles before proper device operation is achieved.
- V<sub>IH</sub>(min) and V<sub>IL</sub>(max) are reference levels for measuring timing of input signals. Transition times are measured between V<sub>IH</sub>(min) and V<sub>IL</sub>(max) and are assumed to be 5ns for all inputs.
- Measured with a load equivalent to 2 TTL loads and 100pF.
- Operation within the t<sub>RC</sub>D(max) limit insures that t<sub>RC</sub>A(max) can be met. t<sub>RC</sub>D(max) is specified as a reference point only. If t<sub>RC</sub>D is greater than the specified t<sub>RC</sub>D(max) limit, then access time is controlled exclusively by t<sub>C</sub>A.
- Assumes that t<sub>RC</sub>D ≥ t<sub>RC</sub>D(max).
- This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V<sub>OH</sub> or V<sub>OL</sub>.
- t<sub>W</sub>C<sub>S</sub> is non-restrictive operating parameter. It is included in the data sheet as electrical characteristics only. If t<sub>W</sub>C<sub>S</sub> ≥ t<sub>W</sub>C<sub>S</sub>(min), the cycle is an early write cycle and the data out pin will remain high impedance for the duration of the cycle.
- Either t<sub>RC</sub>H or t<sub>RR</sub>H must be satisfied for a read cycle.
- These parameters are referenced to the  $\overline{\text{CAS}}$  leading edge in early write cycles and to the  $\overline{\text{W}}$  leading edge in read-write cycles.
- Operation within the t<sub>RA</sub>D(max) limit insures that t<sub>RC</sub>A(max) can be met. t<sub>RA</sub>D(max) is specified as reference point only. If t<sub>RA</sub>D is greater than the specified t<sub>RA</sub>D(max) limit, then access time is controlled by t<sub>A</sub>A.
- t<sub>C</sub>E<sub>Z</sub>(max), t<sub>R</sub>E<sub>Z</sub>(max), t<sub>W</sub>E<sub>Z</sub>(max) and t<sub>O</sub>E<sub>Z</sub>(max) define the time at which the output achieves the open circuit condition and are not referenced to output voltage level.
- If  $\overline{\text{RAS}}$  goes to high before  $\overline{\text{CAS}}$  high going, the open circuit condition of the output is achieved by  $\overline{\text{CAS}}$  high going. If  $\overline{\text{CAS}}$  goes to high before  $\overline{\text{RAS}}$  high going, the open circuit condition of the output is achieved by  $\overline{\text{RAS}}$  high going.
- t<sub>ASC</sub> ≥ t<sub>CP</sub> min

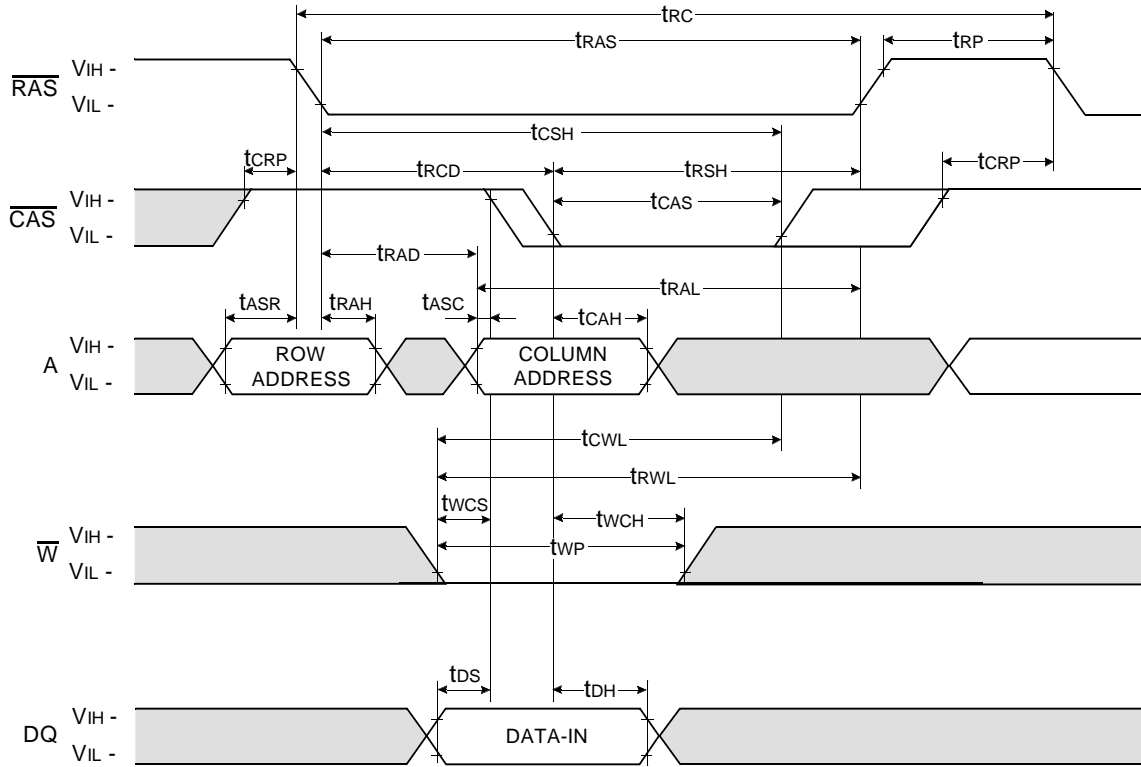
READ CYCLE



Don't care  
 Undefined

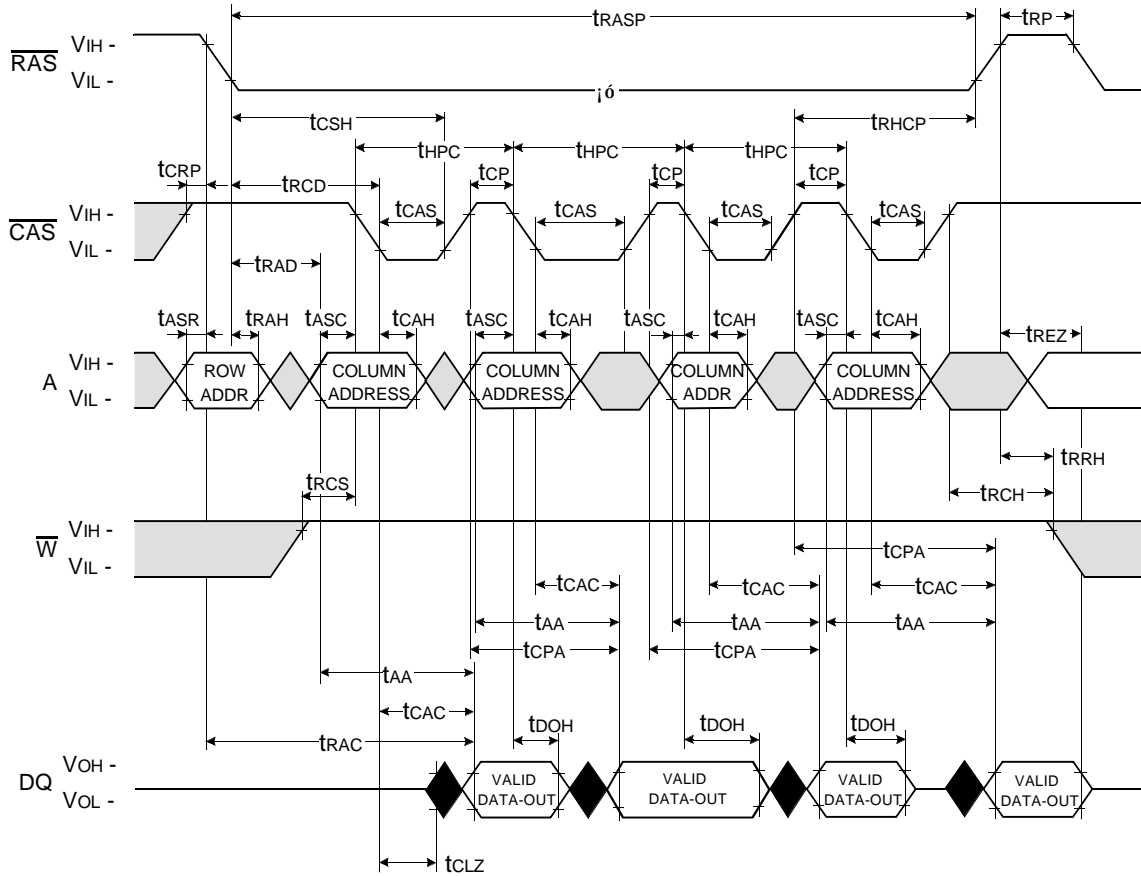
WRITE CYCLE ( EARLY WRITE )

NOTE : DOUT = OPEN



□ Don't care  
■ Undefined

HYPER PAGE READ CYCLE

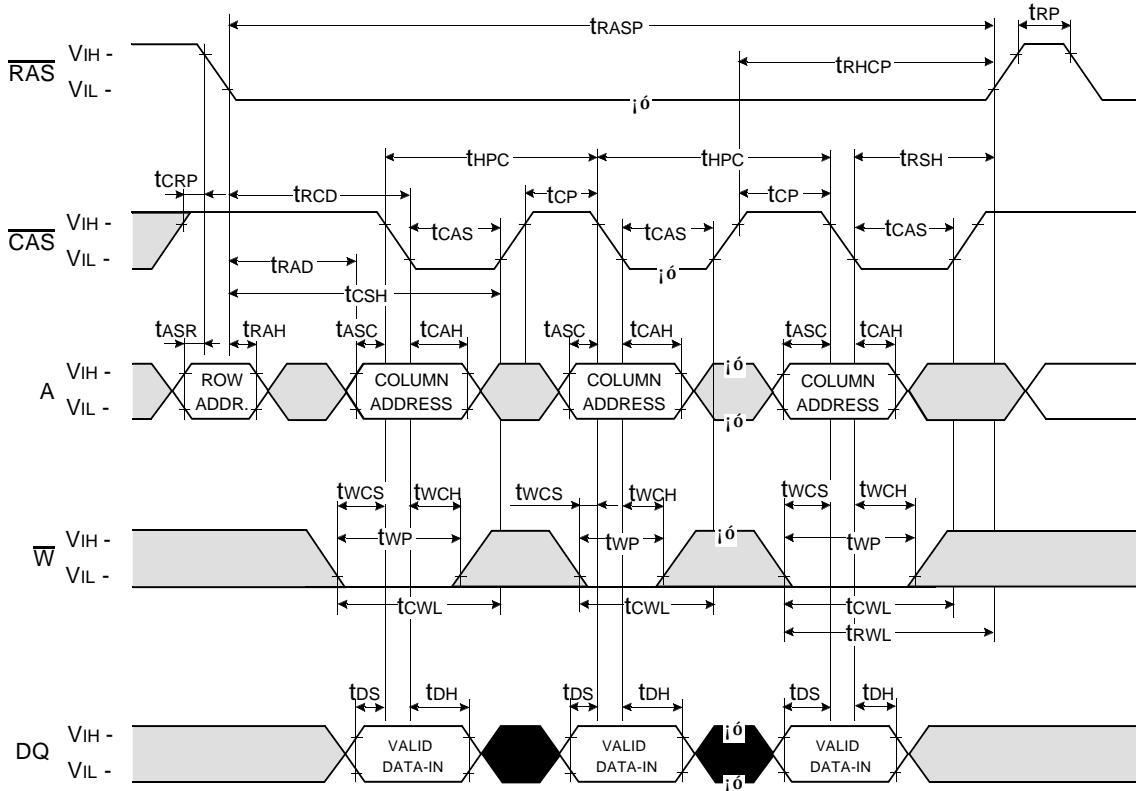


Don't care  
 Undefined



**HYPER PAGE WRITE CYCLE ( EARLY WRITE )**

NOTE : DOUT = OPEN

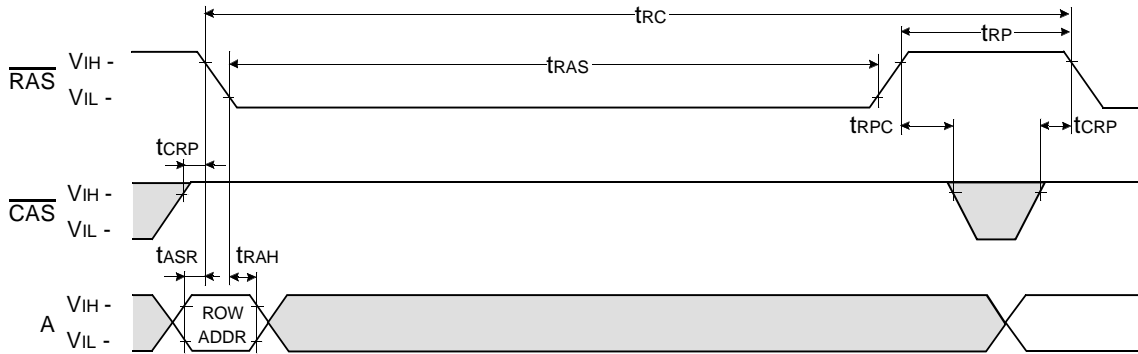


Don't care  
 Undefined

**$\overline{\text{RAS}}$  - ONLY REFRESH CYCLE\***

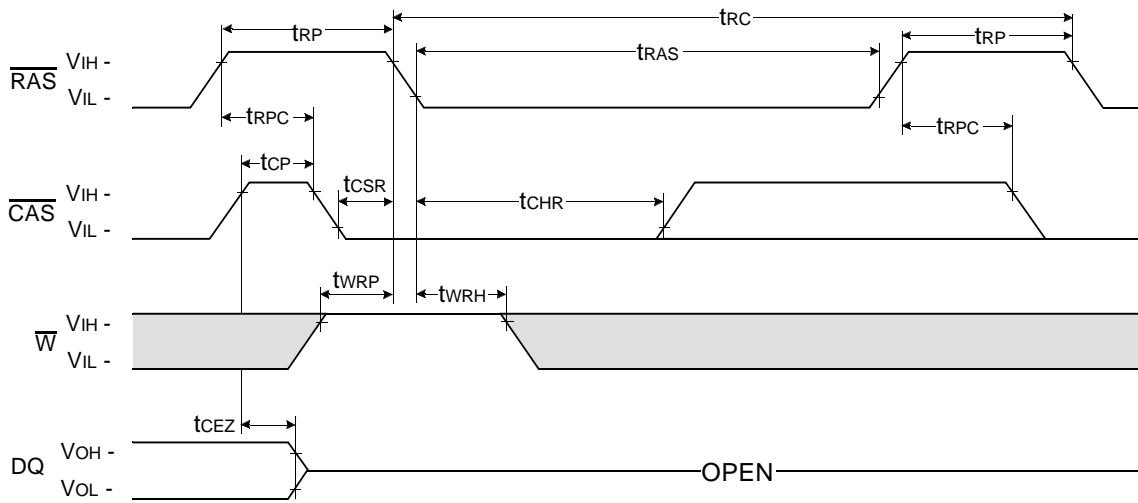
NOTE :  $\overline{\text{W}}$ ,  $\overline{\text{OE}}$ , DIN = Don't care

DOUT = OPEN



**$\overline{\text{CAS}}$  - BEFORE -  $\overline{\text{RAS}}$  REFRESH CYCLE**

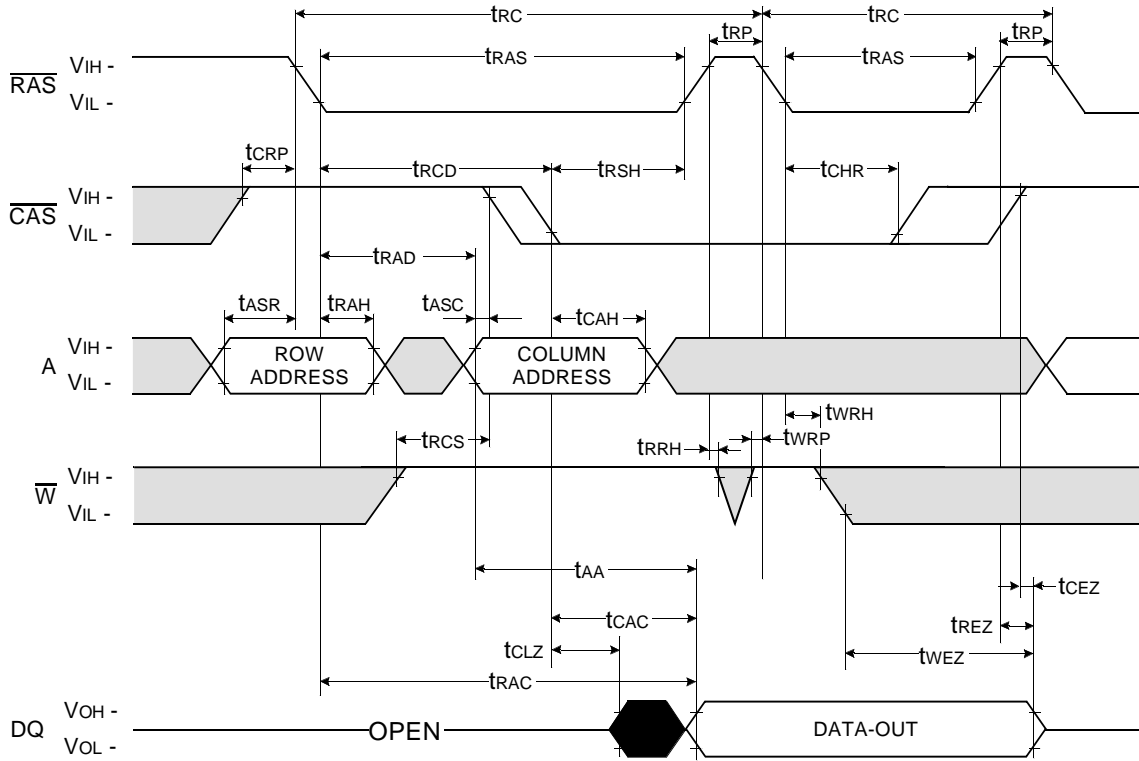
NOTE :  $\overline{\text{OE}}$ , A = Don't care



Don't care  
 Undefined

\* In  $\overline{\text{RAS}}$ -only refresh cycle of 64Mb A-die & B-die, when  $\overline{\text{CAS}}$  signal transits from Low to High, the valid data may be cut off.

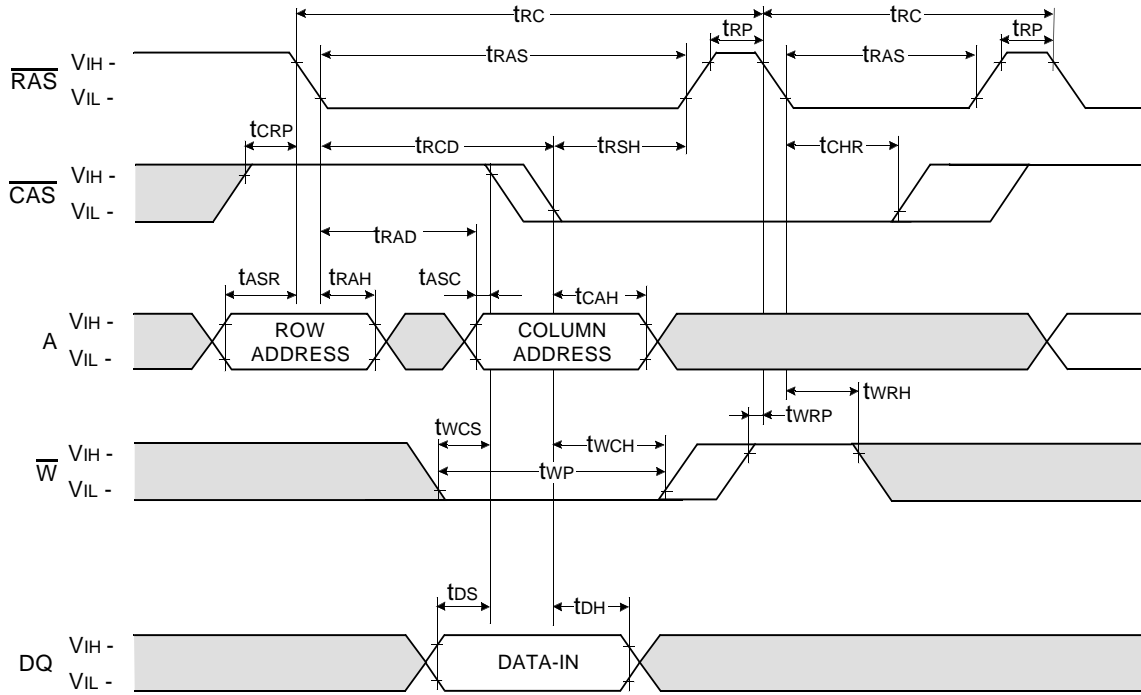
HIDDEN REFRESH CYCLE ( READ )



Don't care  
 Undefined

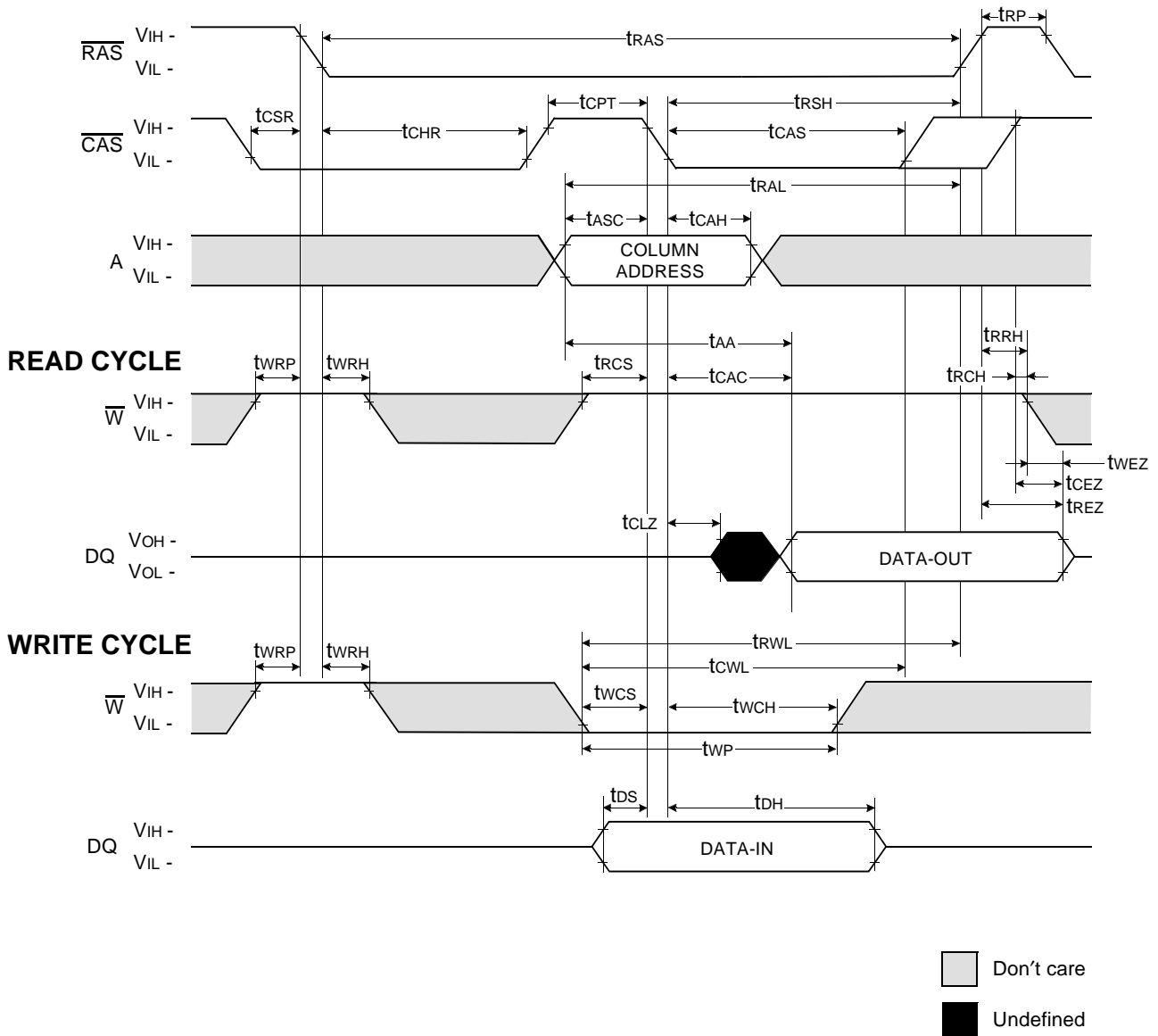
**HIDDEN REFRESH CYCLE ( WRITE )**

NOTE : DOUT = OPEN



Don't care  
 Undefined

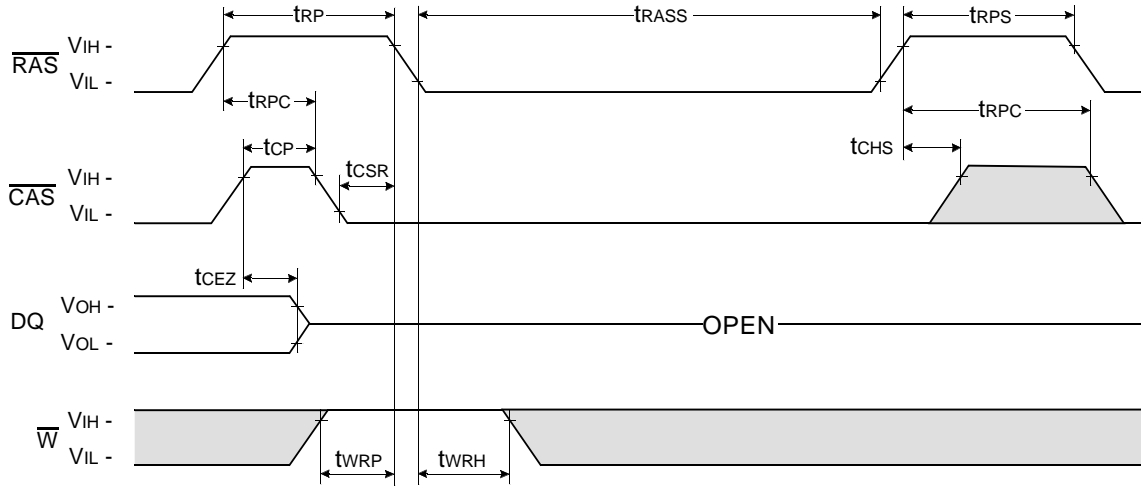
**CAS-BEFORE-RAS REFRESH COUNTER TEST CYCLE**



NOTE : This timing diagram is applied to all devices besides 64M DRAM based modules.

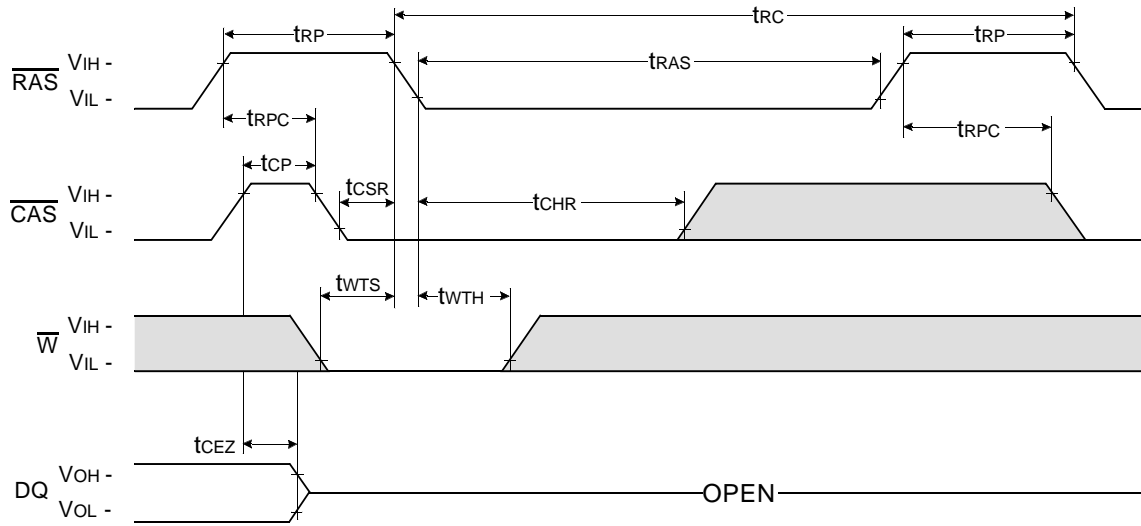
**$\overline{\text{CAS}}$  - BEFORE -  $\overline{\text{RAS}}$  SELF REFRESH CYCLE**

NOTE :  $\overline{\text{OE}}$ , A = Don't care



**TEST MODE IN CYCLE**

NOTE :  $\overline{\text{OE}}$ , A = Don't care



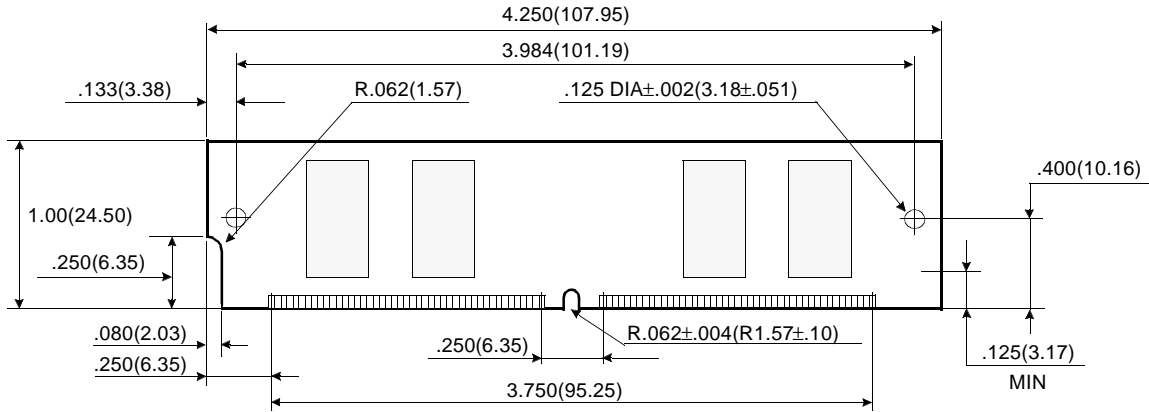
Don't care  
 Undefined

# DRAM MODULE

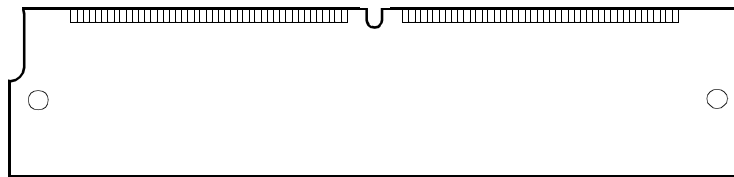
# KMM5322104CKU/CKUG

## PACKAGE DIMENSIONS

Units : Inches (millimeters)

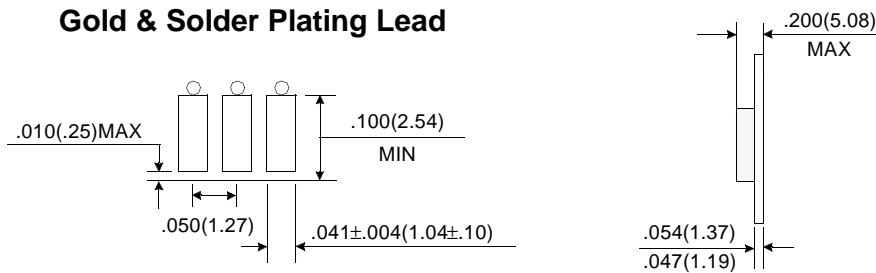


( Front view )



( Back view )

### Gold & Solder Plating Lead



Tolerances : ±.005(.13) unless otherwise specified

NOTE : The used device is 2Mx8 DRAM

DRAM Part No. : KMM5322104CKU/CKUG -- KM48C2104CK (300mil)

Revision History

Rev 0.0 : Aug. 1997.



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